

NOTES :

1. MATERIAL :

HOUSING : POLYESTER ,UL94V-0 ,
 COLOR:BLACK, OR WHITE
 TERMINAL : PHOSPHOR BRONZE (PhBr)
 METAL SHELL : COPPER ALLOY

2. PLATING :

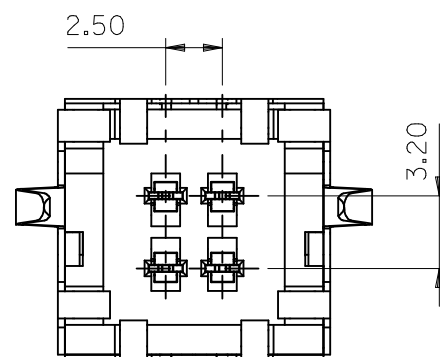
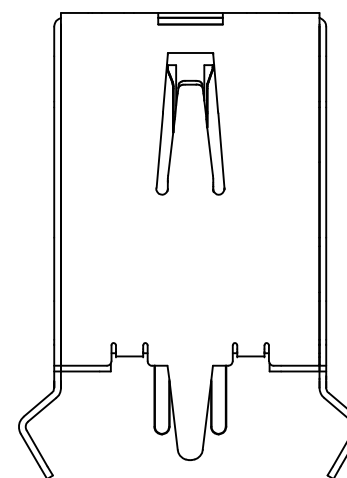
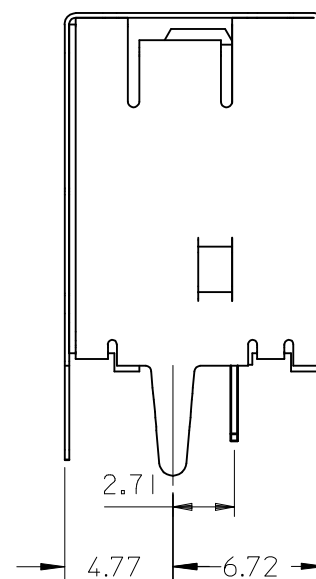
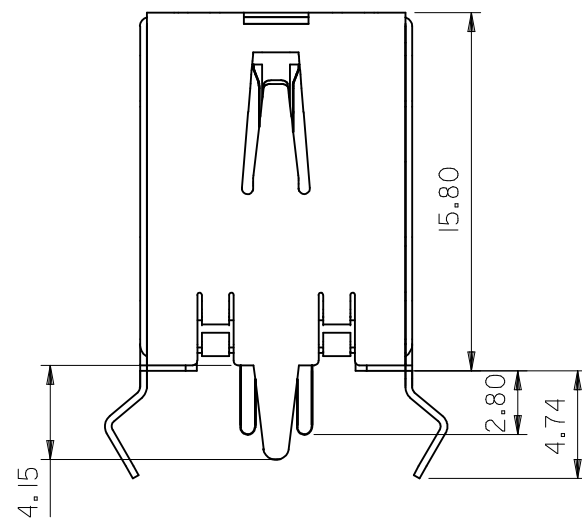
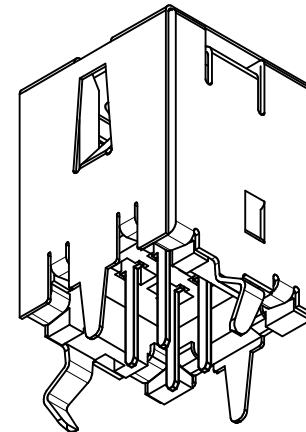
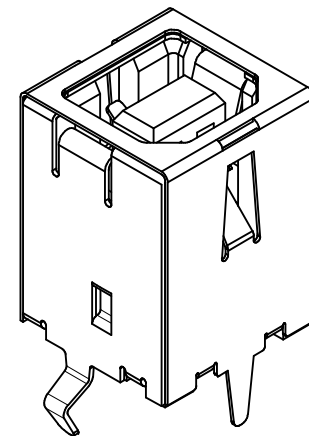
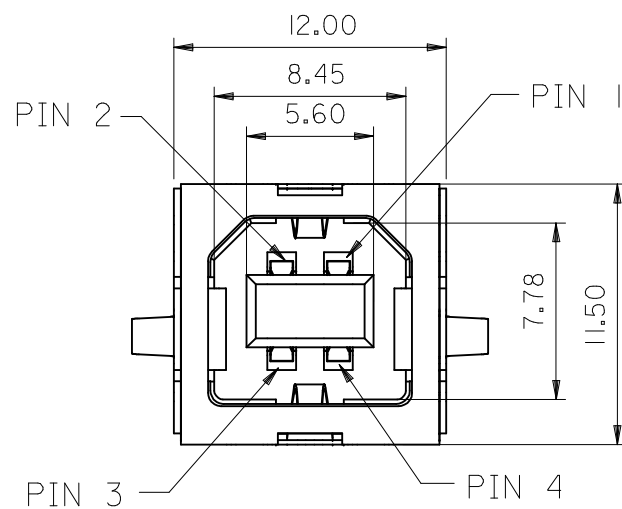
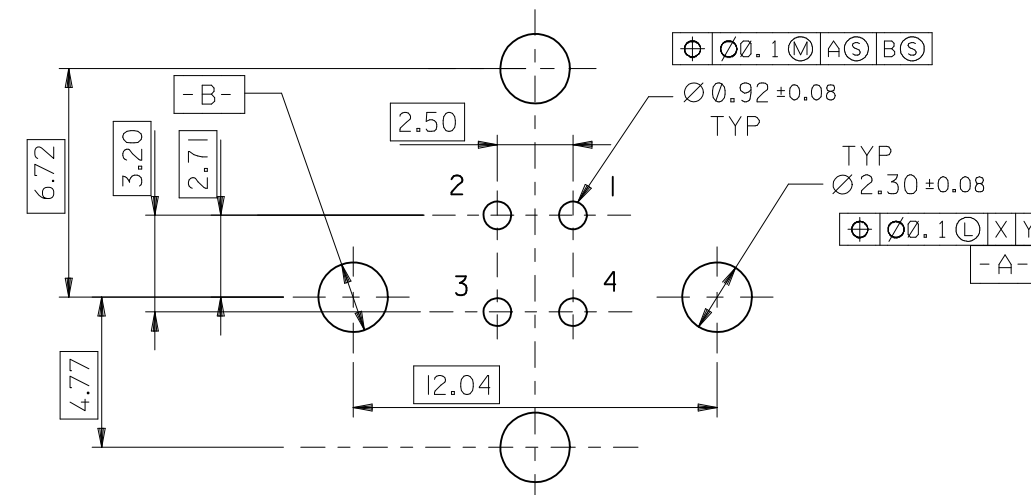
TERMINAL :
 CONTACT AREA :
 (a) GOLD FLASH.
 (b) GOLD (Au), THICKNESS=30 MICROINCH /0.76 MICROMETER
 SOLDER TAIL : (a) TIN-LEAD (90/10) ALLOY
 ,THICKNESS=150 MICROINCH/3.8 MICROMETER
 (b) PURE TIN PLATING,
 THICKNESS=50 MICROINCH/1.27MICROMETER MINIMUM.
 UNDER PLATE : NICKEL (Ni)
 ,THICKNESS=50 MICROINCH /1.27 MICROMETER

METAL SHELL :

(a) TIN-LEAD (Sn-Pb) ALLOY
 ,THICKNESS=100 MICROINCH /2.54 MICROMETER
 (b) PURE TIN PLATING,
 THICKNESS =50 MICROINCH/1.27 MICROMETER MINIMUM.
 UNDER PLATE : NICKEL (Ni)
 ,THICKNESS=50 MICROINCH /1.27 MICROMETER

3. RECOMMENDED PCB THICKNESS : 1.60±0.05mm

4. PRODUCT SPECIFICATION : REFER TO PS-67998-0000



REVISED EC NO: DRWN:YPWU CHKD: APPR: G	2009/09/01	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		USB B VERTICAL CONN			
				▽=0 ▽C=0		mm	INCH	DRAWN BY SAM SHIN	DATE 1998/12/21	TITLE MOLEX INCORPORATED						
					4 PLACES	± ---	± ---	CHECKED BY VLIN	DATE 1998/12/21							
					3 PLACES	± ---	± ---	APPROVED BY	DATE							
					2 PLACES	± 0.25	± ---	NEGATIVE LIN	DATE 1998/12/21							
					1 PLACE	± 0.25	± ---	MATERIAL NO. SEE TABLE								DOCUMENT NO. SD-67265-002
				ANGULAR ± 3 °												
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS												

